

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t14661cn8#pbf

(Engineering Calculation)

PDIP

(printed on: 2020-07-11 18:34:01)

**TOTAL MASS (g) : 0.501712**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.004326	1000000	8622.47167969		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000241	1000000	480.354980469		
Lead Frame	A42	Copper (Cu)	7440-50-8	0.000000	0	0		
		Iron (Fe)	7439-89-6	0.089088	580000	177567.90625		
		Phosphorus (P)	7723-14-0	0.000000	0	0		
		Zinc (Zn)	7440-66-6	0.000000	0	0		
		Nickel (Ni)	7440-02-0	0.064512	420000	128583.640625		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.153600</b>	<b>1000000</b>	<b>306151.5625</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.012410	1000000	24735.8691406		
		<b>External Plating Total:</b>				<b>0.012410</b>	<b>1000000</b>	<b>24735.8691406</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001228	1000000	2447.61791992		
<b>Internal Plating Total:</b>				<b>0.001228</b>	<b>1000000</b>	<b>2447.61791992</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001177	750000	2345.96582031		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000392	250000	781.32421875		
<b>Die Attach Total:</b>				<b>0.001569</b>	<b>1000000</b>	<b>3127.2902832</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.044287	135000	88271.703125		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.282125	860000	562324.25		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.001640	5000	3268.80566406		
		<b>Encapsulation Total:</b>				<b>0.328052</b>	<b>1000000</b>	<b>653864.8125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000286	1000000	570.047790527		
					<b>TOTAL MASS (g) :</b>	<b>0.501712</b>		